

FRED Module

Fast Recovery Epitaxial Diode

$V_{RRM} = 600\text{ V}$
 $I_{FAVM} = 304\text{ A}$
 $t_{rr} = 250\text{ ns}$


Part number

MEA 300-06DA

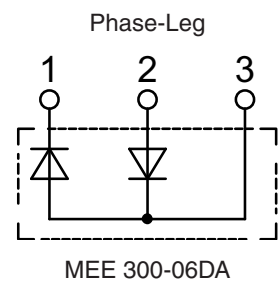
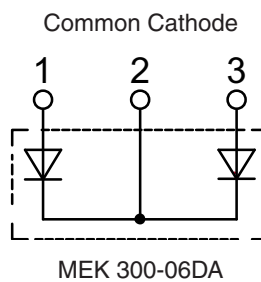
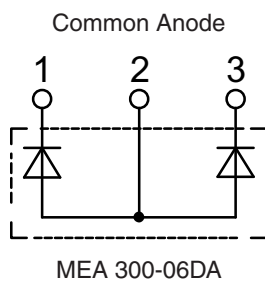
MEK 300-06DA

MEE 300-06DA



 E72873

Backside: isolated



Features / Advantages:

- International standard package with DCB ceramic base plate
- Planar passivated chips
- Short recovery time
- Low switching losses
- Soft recovery behaviour
- High reliability circuit operation
- Low voltage peaks for reduced protection circuits
- Low noise switching
- Low losses

Applications:

- Antiparallel diode for high frequency switching devices
- Free wheeling diode in converters and motor control circuits
- Inductive heating and melting
- Uninterruptible power supplies (UPS)
- Ultrasonic cleaners and welders

Package: Y4-M6

- Isolation voltage: 3600 V~
- Industry standard outline
- Soldering pins for PCB mounting
- Base plate: DCB ceramic
- Reduced weight
- Advanced power cycling

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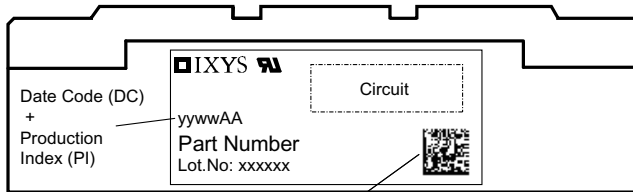
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Diode				Ratings			
Symbol	Definitions	Conditions	min.	typ.	max.		
V_{RSM}	max. non-repetitive reverse				600	V	
V_{RRM}	max. repetitive reverse				600	V	
I_R	reverse current	$V_R = V_{RRM}$			12	mA	
		$V_R = 0.8 \cdot V_{RRM}$			3	mA	
		$V_R = 0.8 \cdot V_{RRM}$			80	mA	
V_F	forward voltage	$I_F = 300$ A			1.27	V	
					1.05	V	
		$I_F = 520$ A			1.36	V	
					1.19	V	
I_{FRMS}	RMS forward current				430	A	
I_{FAV} ①	average forward current	$T_C = 75^\circ\text{C}$ rectangular, d = 0.5			304	A	
V_{TO}	threshold voltage	for power-loss calculations only			0.85	V	
r_T	slope resistance				1.34	m Ω	
R_{thJC}	thermal resistance junction to case			0.085	0.143	K/W	
R_{thCH}	thermal resistance junction to heatsink					K/W	
P_{tot}	total power dissipation				875	W	
I_{FSM}	max. surge forward current	t = 10 ms (50 Hz), sine			2.40	kA	
		t = 8.3 ms (60 Hz), sine			2.64	kA	
		t = 10 ms (50 Hz), sine			2.16	kA	
		t = 8.3 ms (60 Hz), sine			2.38	kA	
I^2t	I^2t value for fusing	t = 10 ms (50 Hz), sine			28.8	kA ² s	
		t = 8.3 ms (60 Hz), sine			29.3	kA ² s	
		t = 10 ms (50 Hz), sine			23.3	kA ² s	
		t = 8.3 ms (60 Hz), sine			23.8	kA ² s	
t_{rr}	max. reverse recovery current	$I_F = 300$ A; $-di_F/dt = 400$ A/ μ s			140	170	ns
					250	300	ns
I_{RM}	reverse recovery time	$V_R = 300$ V; $L \leq 0.05$ μ H			35	45	A
					55	70	A

① I_{FAVM} rating includes reverse blocking losses at T_{VJM} , $V_R = 0.8 V_{RRM}$, duty cycle d = 0.5

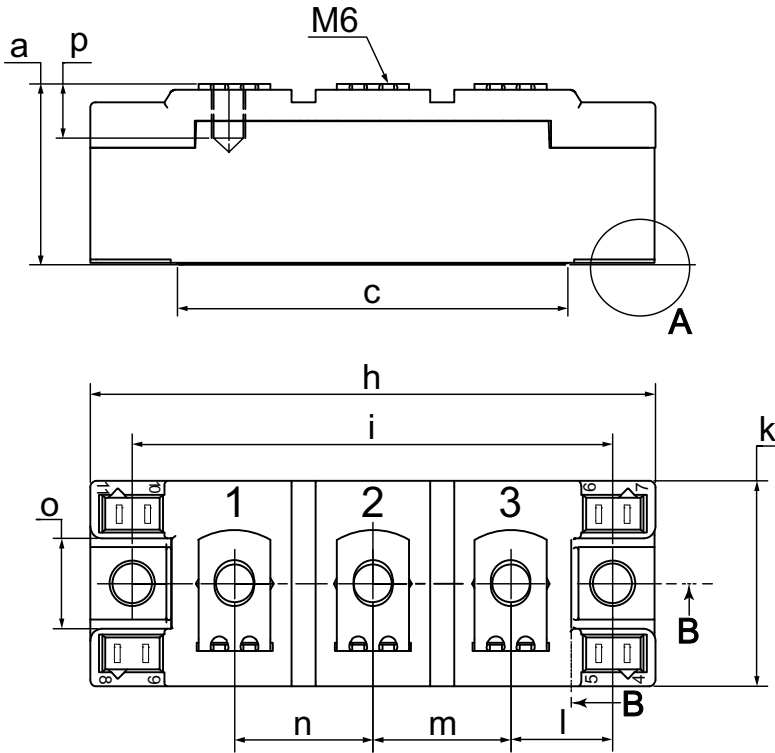


Package Y4-M6				Ratings		
Symbol	Definitions	Conditions	min.	typ.	max.	
I_{RMS}	RMS current	per terminal			300	A
T_{VJ}	virtual junction temperature		-40		150	°C
T_{op}	operation temperature		-40		125	°C
T_{stg}	storage temperature		-40		125	°C
Weight					126	g
M_D	mounting torque		2.25		2.75	Nm
M_T	terminal torque		4.5		5.5	Nm
$d_{Spp/App}$	creepage distance on surface striking distance through air	terminal to terminal	14.0	10.0		mm
$d_{Spb/Appb}$		terminal to backside	16.0	16.0		mm
V_{ISOL}	isolation voltage	t = 1 second t = 1 minute	50/60 Hz, RMS; $I_{ISOL} \leq 1$ mA		3600 3000	V V

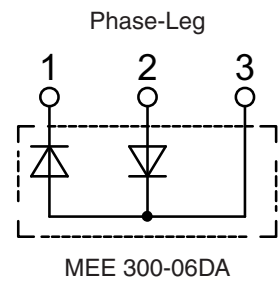
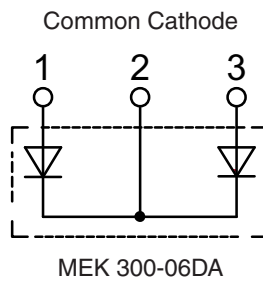
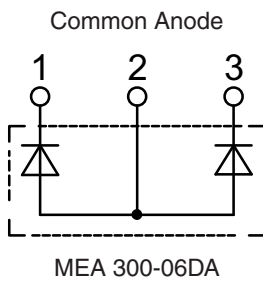
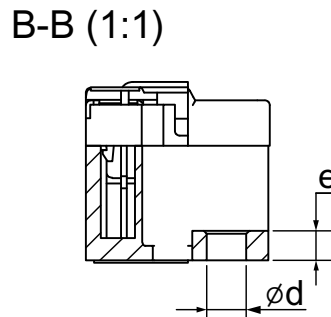
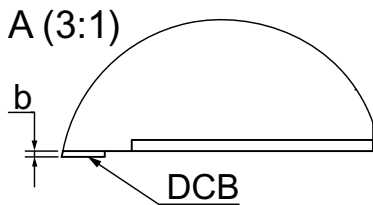


Data Matrix: part no. (1-19), DC + PI (20-25), lot.no.# (26-31), blank (32), serial no.# (33-36)

Ordering	Part Name	Marking on Product	Delivering Mode	Base Qty	Ordering Code
Standard	MEA 300-06DA	MEA 300-06DA	Box	36	464686
Standard	MEK 300-06DA	MEK 300-06DA	Box	36	464619
Standard	MEE 300-06DA	MEE 300-06DA	Box	36	464708

Outlines Y4-M6


Dim.	min [mm]	max [mm]	min [inch]	max [inch]
a	30.0	30.6	1.181	1.205
b	typ. 0.25		typ. 0.010	
c	64.0	65.0	2.520	2.559
d	6.5	7.0	0.256	0.275
e	4.9	5.1	0.193	0.201
h	93.5	94.5	3.681	3.720
i	79.5	80.5	3.130	3.169
k	33.4	34.0	1.315	1.339
l	16.7	17.3	0.657	0.681
m	22.7	23.3	0.894	0.917
n	22.7	23.3	0.894	0.917
o	14.0	15.0	0.551	0.591
p	typ. 10.5		typ. 0.413	



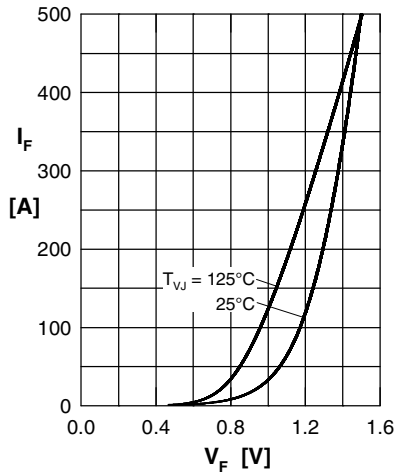
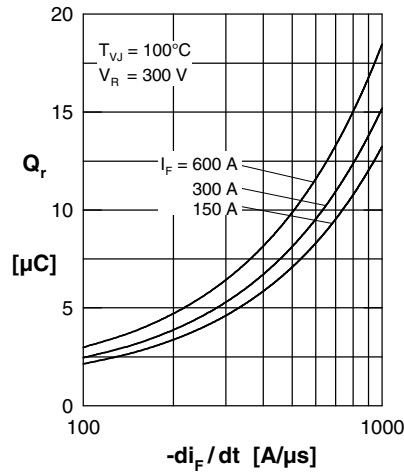
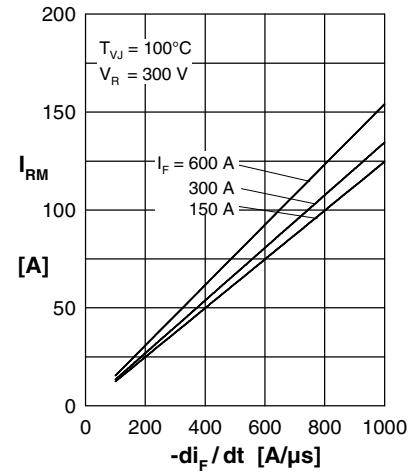
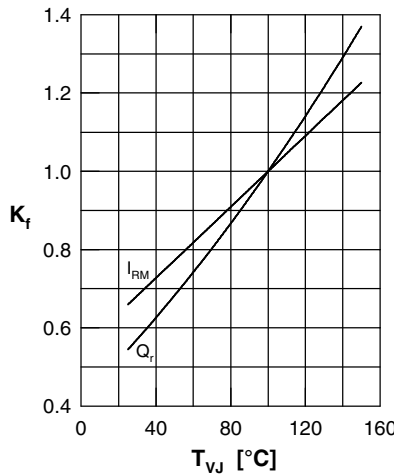
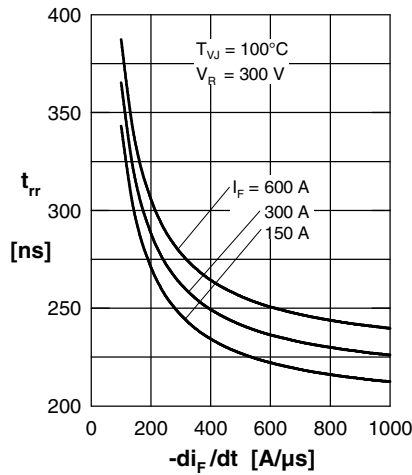
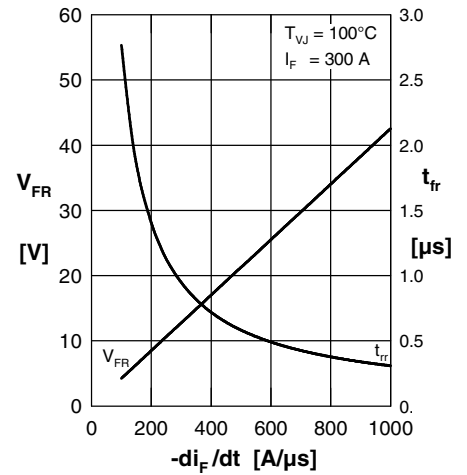
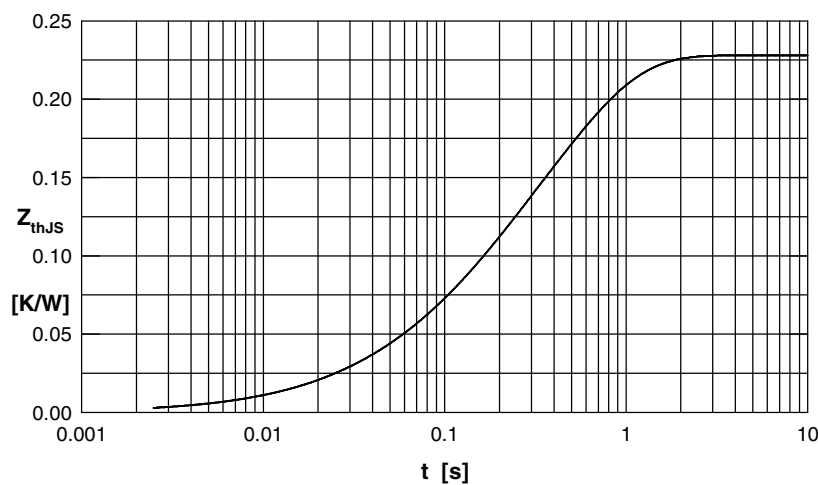
Curves

 Fig. 1 Typ. forward current I_F versus max. voltage drop V_F per leg

 Fig. 2 Typ. reverse recovery charge Q_r versus $-di_F/dt$

 Fig. 3 Typ. peak reverse current I_{RM} versus $-di_F/dt$

 Fig. 4 Typ. dynamic parameters Q_r , I_{RM} versus junction temperature T_{VJ}

 Fig. 5 Typ. recovery time t_{rr} versus $-di_F/dt$

 Fig. 6 Typ. peak forward voltage V_{FR} and t_{rr} versus $-di_F/dt$


Fig. 7 Typ. transient thermal impedance junction to heatsink

 Constants for Z_{thJS} calculation:

i	R_{thi} [K/W]	t_i [s]
1	0.002	0.080
2	0.008	0.024
3	0.054	0.112
4	0.164	0.464